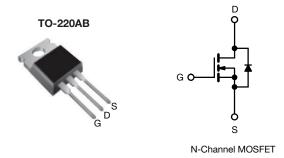
HALOGEN FREE

Vishay Siliconix

D Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	550				
R _{DS(on)} max. (Ω) at 25 °C	V _{GS} = 10 V 1.5				
Q _g max. (nC)	20				
Q _{gs} (nC)	3				
Q _{gd} (nC)	5				
Configuration	Single				



FEATURES

- Optimal design
 - Low area specific on-resistance
 - Low input capacitance (Ciss)
 - Reduced capacitive switching losses
 - High body diode ruggedness
 - Avalanche energy rated (UIS)
- Optimal efficiency and operation
 - Low cost
 - Simple gate drive circuitry
 - Low figure-of-merit (FOM): Ron x Qg
 - Fast switching
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Consumer electronics
 - Displays (LCD or plasma TV)
- Server and telecom power supplies
 - SMPS
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- · Battery chargers

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	SiHP5N50D-E3			
Lead (Pb)-free and Halogen-free	SiHP5N50D-GE3			

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	500		
Gate-Source Voltage			.,	± 30	V	
Gate-Source Voltage AC (f > 1 Hz)	V _{GS}	30				
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	$\frac{T_C = 25 \text{ °C}}{T_C = 100 \text{ °C}}$,	5.3		
	V _{GS} at 10 v	T _C = 100 °C	l _D	3.4	Α	
Pulsed Drain Current ^a	I _{DM}	10				
Linear Derating Factor				0.83	W/°C	
Single Pulse Avalanche Energy ^b	E _{AS}	28.8	mJ			
Maximum Power Dissipation	P _D	104	W			
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +150	°C	
Drain-Source Voltage Slope	T _J = 125 °C		dV/dt	24	\//na	
Reverse Diode dV/dt ^d			av/at	0.28	- V/ns	
Soldering Recommendations (Peak temperatur	k temperature) c for 10 s			300	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 2.3 mH, R_q = 25 Ω , I_{AS} = 5 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, starting $T_J = 25$ °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R _{thJC}	-	1.2	G/ VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static				•	I.	•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		500	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	e to 25 °C, I _D = 250 μA	-	0.58	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	5	V
Gate-Source Leakage	I _{GSS}	,	V _{GS} = ± 30 V		-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		-	-	1	μА
Zero date voltage Brain ourrent	DSS	$V_{DS} = 400 \text{ V}$	V _{DS} = 400 V, V _{GS} = 0 V, T _J = 125 °C		-	10	
Drain-Source On-State Resistance	R _{DS(on)}	$V_{GS} = 10 \text{ V}$	$I_D = 2.5 A$	-	1.2	1.5	Ω
Forward Transconductance a	9 _{fs}	V _{DS} :	= 20 V, I _D = 2.5 A	-	1.8	-	S
Dynamic							
Input Capacitance	C_{iss}		$V_{GS} = 0 V$	-	325	-	
Output Capacitance	C_{oss}	,	$V_{DS} = 100 \text{ V},$	-	34	-	
Reverse Transfer Capacitance	C_{rss}		f = 1 MHz	-	6	-	
Effective Output Capacitance, Energy Related ^b	$C_{o(er)}$	V _{DS} = 0 V to 400 V, V _{GS} = 0 V		-	31	-	pF
Effective Output Capacitance, Time Related ^c	C _{o(tr)}			-	41	-	
Total Gate Charge	Qg			-	10	20	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 2.5 \text{ A}, V_{DS} = 400 \text{ V}$		3	-	nC
Gate-Drain Charge	Q _{gd}			-	5	-	
Turn-On Delay Time	t _{d(on)}			-	12	24	1
Rise Time	t _r	V _{DD} =	$V_{DD} = 400 \text{ V}, I_{D} = 2.5 \text{ A}$ $R_{g} = 9.1 \Omega, V_{GS} = 10 \text{ V}$		11	22	ns
Turn-Off Delay Time	t _{d(off)}				14	28	
Fall Time	t _f				11	22	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	1.7	-	Ω
Drain-Source Body Diode Characteristic	s			•			
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse P - N junction diode		-	-	5	
Pulsed Diode Forward Current	I _{SM}			-	-	20	A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 4 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = I _S = 2.5 A, dl/dt = 100 A/ μ s, V _R = 20 V		-	320	-	ns
Reverse Recovery Charge	Q_{rr}			-	1.2	-	μC
Reverse Recovery Current	I _{RRM}			-	8	-	A

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .
- c. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

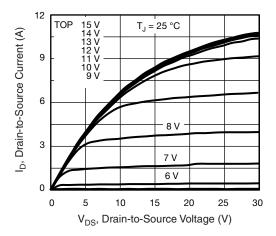


Fig. 1 - Typical Output Characteristics

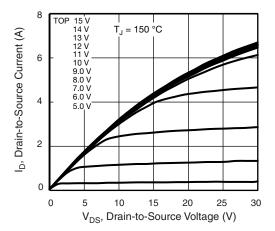


Fig. 2 - Typical Output Characteristics

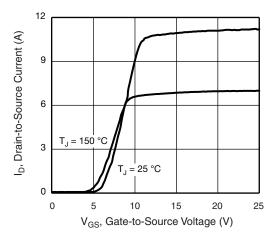


Fig. 3 - Typical Transfer Characteristics

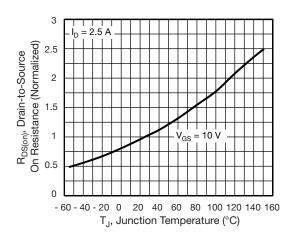


Fig. 4 - Normalized On-Resistance vs. Temperature

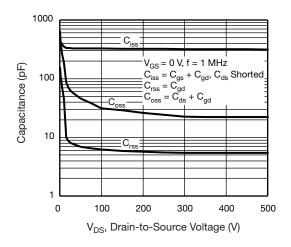


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

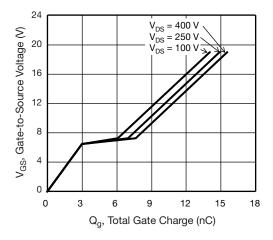


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



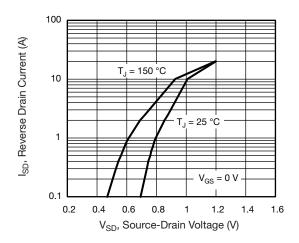


Fig. 7 - Typical Source-Drain Diode Forward Voltage

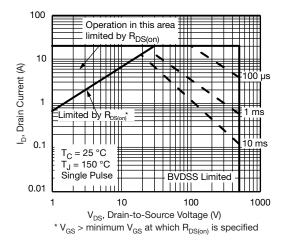


Fig. 8 - Maximum Safe Operating Area

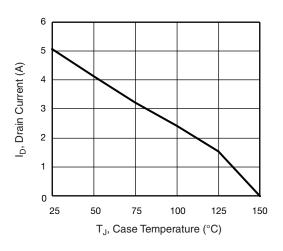


Fig. 9 - Maximum Drain Current vs. Case Temperature

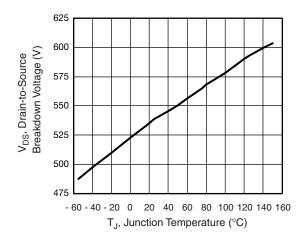


Fig. 10 - Typical Drain-to-Source Voltage vs. Temperature

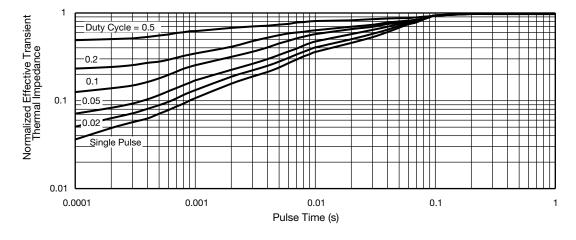


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case

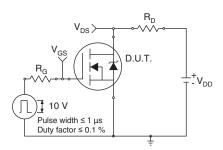


Fig. 12 - Switching Time Test Circuit

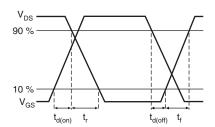


Fig. 13 - Switching Time Waveforms

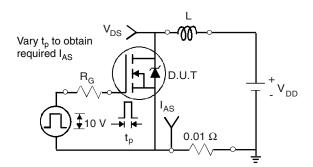


Fig. 14 - Unclamped Inductive Test Circuit

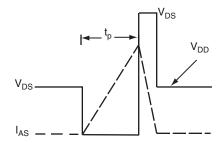


Fig. 15 - Unclamped Inductive Waveforms

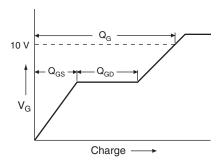


Fig. 16 - Basic Gate Charge Waveform

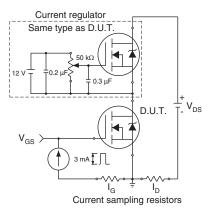
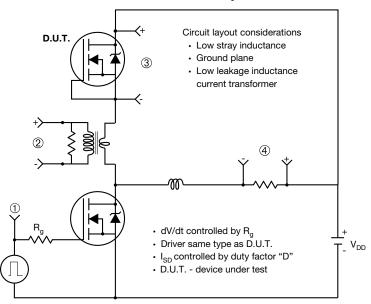


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



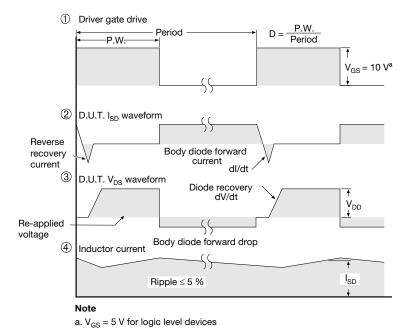


Fig. 18 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?91489.





TO-220-1



DIM	MILLIN	IETERS	INCHES			
DIM.	MIN.	MAX.	MIN.	MAX.		
Α	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
E	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: X15-0364-Rev. C, 14-Dec-15 DWG: 6031						

Note

 \bullet $M^{\star}=0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



Revison: 14-Dec-15 1 Document Number: 66542



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